

Amendments to the Specification

Please replace paragraph [0002] with the following amended paragraph:

This application is related to U.S. Application No. 10/632,568, titled “Semiconductor multi-package module having package stacked over ball grid array package and having wire bond interconnect between stacked packages”; U.S. Application No. 10/632,551, which issued January 4, 2005 as U.S. Patent No. 6,838,761, titled “Semiconductor multi-package module having wire bond interconnect between stacked packages and having electrical shield”; U.S. Application No. 10/632,552, titled “Semiconductor multi-package module having package stacked over die-up flip chip ball grid array package and having wire bond interconnect between stacked packages”; U.S. Application No. 10/632,553, titled “Semiconductor multi-package module having package stacked over die-down flip chip ball grid array package and having wire bond interconnect between stacked packages”; U.S. Application No. 10/632,550, titled “Semiconductor multi-package module including stacked-die packages and having wire bond interconnect between stacked packages”. This application and all the said related applications are being filed on the same date, and each of the said related applications is hereby incorporated herein by reference.